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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/752,642	01/07/2004	Naofumi Nakamura	790001-2042	4109
20999	7590 05/17/2006		EXAMINER	
FROMMER LAWRENCE & HAUG			FENTY, JESSE A	
,	AVENUE- 10TH FL. K, NY 10151		ART UNIT PAPER NUMBER	
NEW TOR	L, 141 10151		2815	
			DATE MAILED: 05/17/200	6

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)	
	10/752,642	NAKAMURA ET AL.	
Office Action Summary	Examiner	. Art Unit.	
	Jesse A. Fenty	2815	
The MAILING DATE of this communication Period for Reply	on appears on the cover sheet w	ith the correspondence address	
A SHORTENED STATUTORY PERIOD FOR I WHICHEVER IS LONGER, FROM THE MAILI - Extensions of time may be available under the provisions of 37 after SIX (6) MONTHS from the mailing date of this communica - If NO period for reply is specified above, the maximum statutory - Failure to reply within the set or extended period for reply will, be Any reply received by the Office later than three months after the earned patent term adjustment. See 37 CFR 1.704(b).	NG DATE OF THIS COMMUN CFR 1.136(a). In no event, however, may a tion. period will apply and will expire SIX (6) MO y statute, cause the application to become A	CATION. reply be timely filed NTHS from the mailing date of this communic BANDONED (35 U.S.C. § 133).	
Status			
 Responsive to communication(s) filed or This action is FINAL. Since this application is in condition for a closed in accordance with the practice u 	☐ This action is non-final. allowance except for formal ma	· •	ts is
Disposition of Claims			
4) ⊠ Claim(s) 1-14 is/are pending in the application 4a) Of the above claim(s) is/are w 5) ⊠ Claim(s) 7-10,13 and 14 is/are allowed. 6) ⊠ Claim(s) 1-3,5,6,11 and 12 is/are rejected 7) ⊠ Claim(s) 4 is/are objected to. 8) □ Claim(s) are subject to restriction	ithdrawn from consideration.		
Application Papers			
9) The specification is objected to by the Ex 10) The drawing(s) filed on is/are: a)[Applicant may not request that any objection Replacement drawing sheet(s) including the 11) The oath or declaration is objected to by	accepted or b) objected to to the drawing(s) be held in abeya correction is required if the drawing	nnce. See 37 CFR 1.85(a). g(s) is objected to. See 37 CFR 1.1	
Priority under 35 U.S.C. § 119			
12) Acknowledgment is made of a claim for f a) All b) Some * c) None of: 1. Certified copies of the priority doc 2. Certified copies of the priority doc 3. Copies of the certified copies of the application from the International * See the attached detailed Office action fo	uments have been received. uments have been received in a ne priority documents have bee Bureau (PCT Rule 17.2(a)).	Application No n received in this National Stage	ē
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-93) Information Disclosure Statement(s) (PTO-1449 or PTO Paper No(s)/Mail Date	Paper No	Summary (PTO-413) (s)/Mail Date Informal Patent Application (PTO-152) 	

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DETAILED ACTION

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 1, 2, 3, 5, 6, 11 and 12 are rejected under 35 U.S.C. 102(e) as being anticipated by Iwasaki et al. (US 2002/0167091 A1).

In re claim 1, Iwasaki (e.g., Fig. 1) discloses a semiconductor device, comprising: at least two wiring layers (19, 15);

a via contact (17) formed between the at least two layers and made of a metal wiring material (aluminum plus copper) which is the same as that of the at least two wiring layers,

wherein the metal wiring material of the via contact contains an additive (copper and nickel or silicon – page 2, paragraph [0027]) which is not contained in the metal wiring materials of the at least two wiring layers.

In re claim 2, Iwasaki discloses the device of claim 1, wherein the metal wiring material comprises copper and the additive is Ni.

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In re claim 3, Iwasaki discloses the device of claim 1, wherein the metal wiring material is Al and the additive is Cu or Si.

In re claim 5, Iwasaki (e.g., Fig. 1) discloses a semiconductor device, comprising: at least two wiring layers (19, 15);

a via contact (17) formed between the at least two layers and made of a metal wiring material (aluminum plus copper) which is the same as that of the at least two wiring layers,

wherein metal wiring materials of the at least two wiring layers contain at least one additive, and a metal wiring material of the via contact contains at least two additives which include an additive which is the same (copper) as that contained in the metal wiring materials of the at least two wiring layers and the at least two wiring layers and an additive which is not contained in the metal wiring materials of the at least two wiring layers (see page 4, last 9 lines of paragraph [0037]).

In re claim 6, Iwasaki discloses the device of claim 5, wherein the metal wiring material comprises copper and the additive is Ni.

In re claim 11, Iwasaki discloses a semiconductor device comprising:

a first metal wiring layer (15) made of a first wiring material, formed in a first wiring groove formed in a first insulating film (13) on a semiconductor substrate (1),

a second insulating film (18) on the first insulating film having the first wiring layer embedded therein,

a via contact (17) embedded in a via hole formed in the second insulating film, the via contact being made of the same wiring material as the first wiring material, which

contain an additive (Ni or Si) which is not contained in the first wiring material of the first wiring layer,

a third insulating film (21) on the second insulating film having the via contact formed therein; and

a second metal wiring layer (19) embedded in a second wiring groove formed in the third insulating film, the second metal wiring layer being made of the same metal wiring material as the metal wiring material of the first metal wiring layer.

In re claim 12, Iwasaki discloses the device of claim 11, wherein the metal wiring material comprises copper and the additive is Ni.

Response to Arguments

Applicant's arguments with respect to claims 1, 2, 5, 6, 11 and 12 were persuasive. Examiner's responses to said arguments are now moot in view of the new ground(s) of rejection.

Allowable Subject Matter

Claim 4 is objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

Claims 7-10, 13 and 14 are allowed.

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Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Jesse A. Fenty whose telephone number is 571-272-1729. The examiner can normally be reached on M-F 5/4.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Ken Parker can be reached on 571-272-2298. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Jesse A. Fenty AU 2815